

General Description

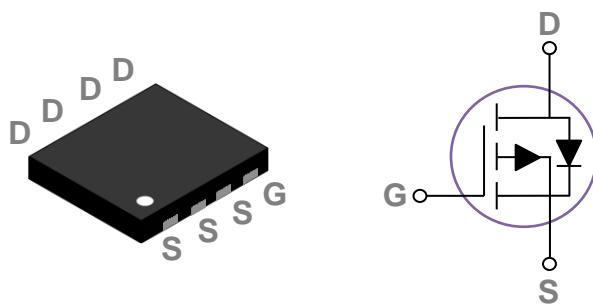
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDS(ON)	ID
-100V	41mΩ	-25A

Features

- -100V,-25A, RDS(ON) 41mΩ@VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

DFN3.3X3.3 Pin Configuration



Applications

- Networking
- Load Switch
- LED applications

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (Tc=25°C)	-25	A
	Drain Current – Continuous (Tc=100°C)	-16	A
I _{DM}	Drain Current – Pulsed ¹	-100	A
EAS	Single Pulse Avalanche Energy ²	180	mJ
IAS	Single Pulse Avalanche Current ²	-60	A
P _D	Power Dissipation (Tc=25°C)	71	W
	Power Dissipation – Derate above 25°C	0.57	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	1.75	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-100	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-80\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	μA
		$V_{DS}=-80\text{V}$, $V_{GS}=0\text{V}$, $T_J=85\text{ }^{\circ}\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-15\text{A}$	---	34	41	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-10\text{A}$	---	44	57	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = -250\mu\text{A}$	-1.2	-1.6	-2.5	V

Dynamic and switching Characteristics³

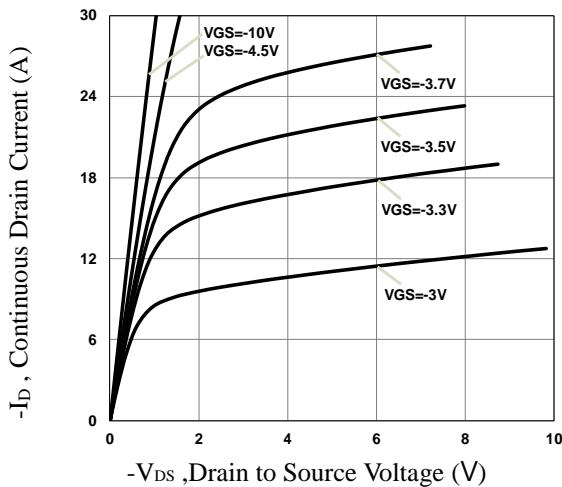
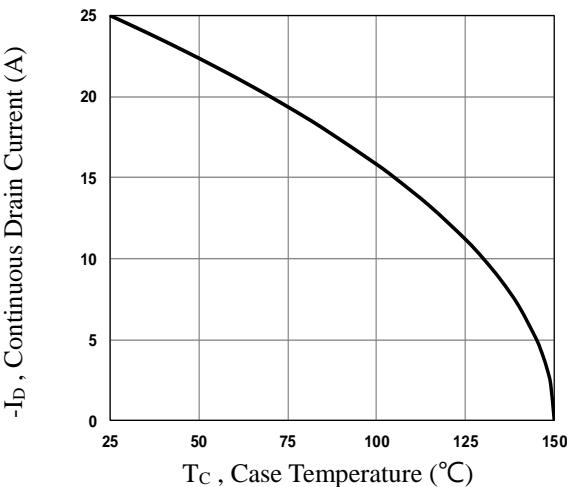
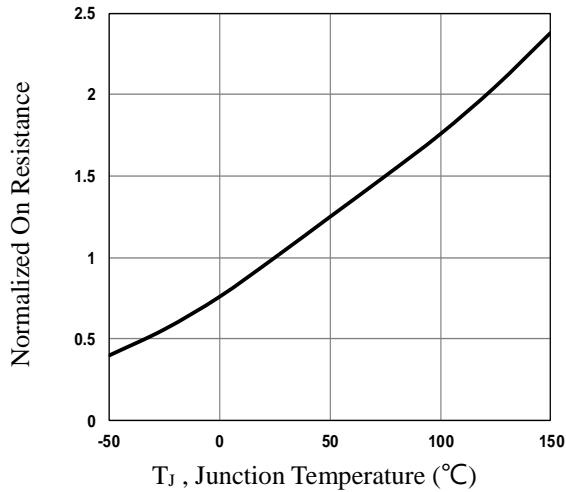
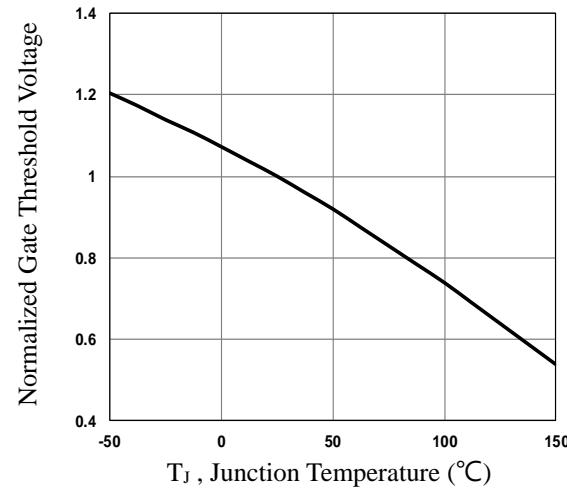
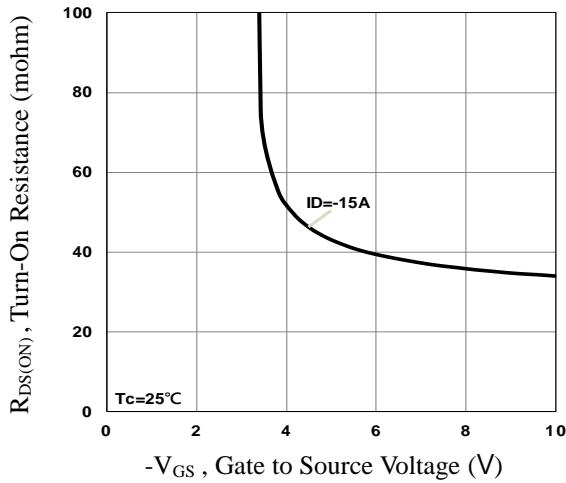
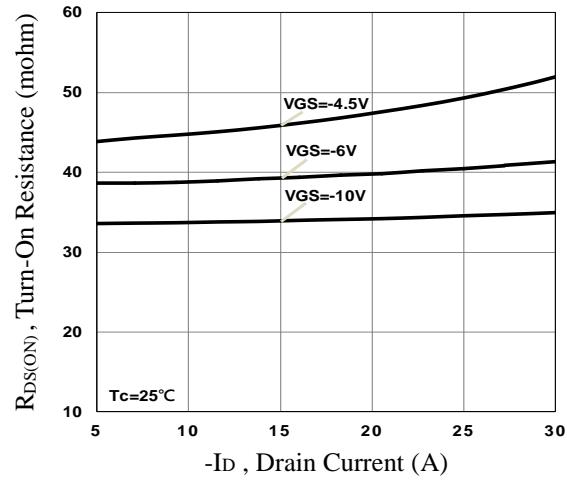
Q_g	Total Gate Charge	$V_{DS}=-50\text{V}$, $V_{GS}=-10\text{V}$, $I_D=-15\text{A}$	---	22	35	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=-50\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-15\text{A}$	---	11	16.5	
Q_{gd}	Gate-Drain Charge		---	1	3	
Q_{gd}			---	4.4	7	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-50\text{V}$, $V_{GS}=-10\text{V}$, $R_G=6\Omega$ $I_D=-15\text{A}$	---	3	5	ns
T_r	Rise Time		---	5	8	
$T_{d(off)}$	Turn-Off Delay Time		---	6	10	
T_f	Fall Time		---	15	25	
C_{iss}	Input Capacitance	$V_{DS}=-50\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	1300	1950	pF
C_{oss}	Output Capacitance		---	340	500	
C_{rss}	Reverse Transfer Capacitance		---	12	20	

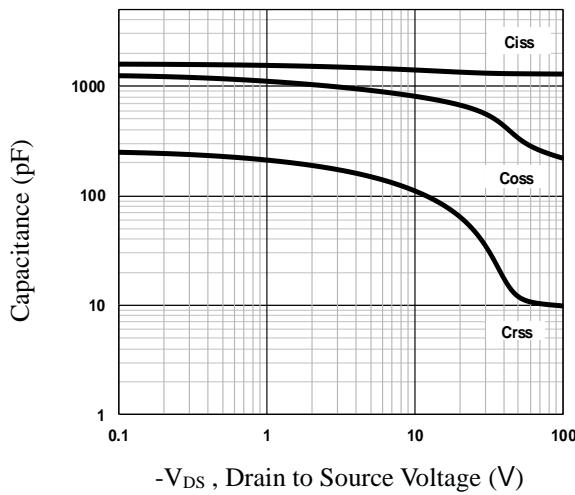
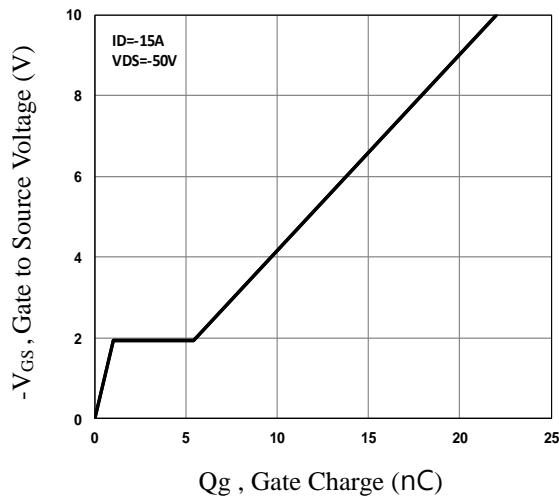
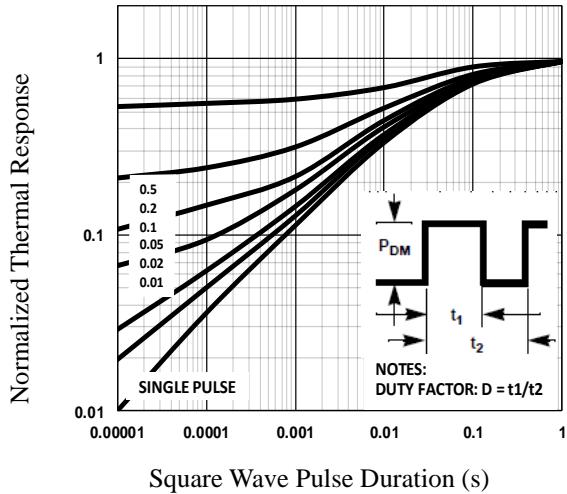
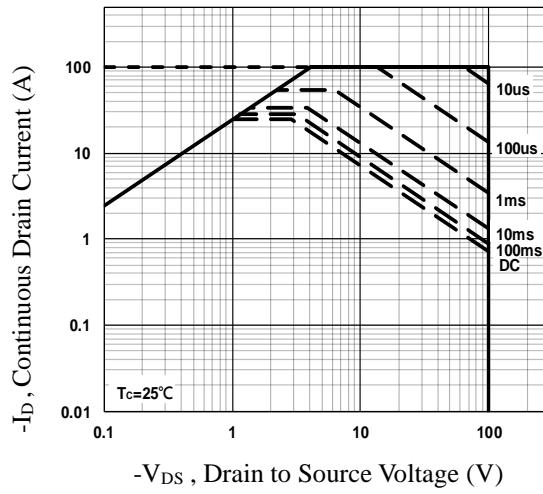
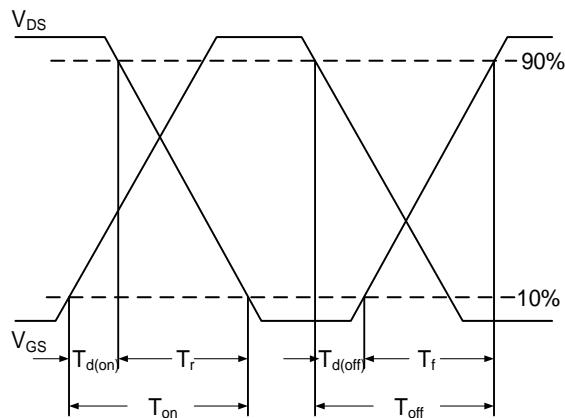
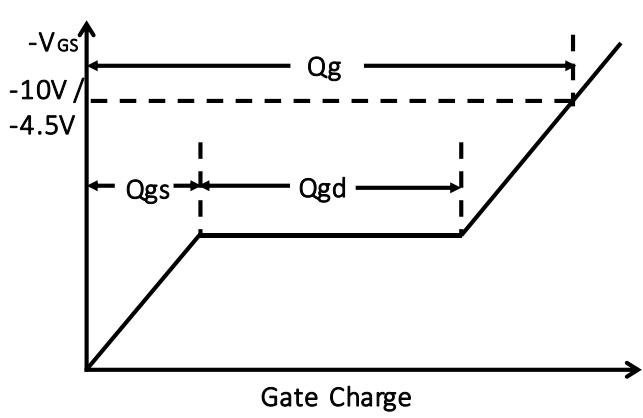
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-25	A
			---	---	-50	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	V
t_{rr}	Reverse Recovery Time	$V_R=-100\text{V}$, $I_s=-10\text{A}$ $di/dt=100\text{A}/\mu\text{s}$, $T_J=25\text{ }^{\circ}\text{C}$	---	170	---	ns
Q_{rr}	Reverse Recovery Charge		---	540	---	nC

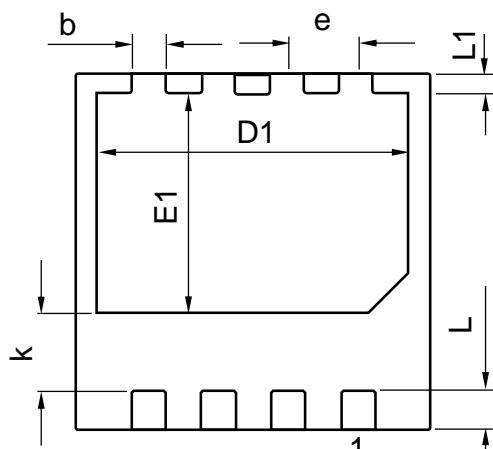
Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- $V_{DD}=-50\text{V}$, $V_{GS}=-10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=-60\text{A}$, Starting $T_J=25\text{ }^{\circ}\text{C}$
- Essentially independent of operating temperature.

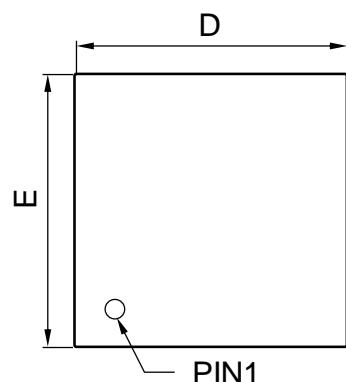

Fig.1 Typical Output Characteristics

Fig.2 Continuous Drain Current vs. T_c

Fig.3 Normalized $R_{DS(ON)}$ vs. T_J

Fig.4 Normalized V_{th} vs. T_J

Fig.5 Turn-On Resistance vs. V_{GS}

Fig.6 Turn-On Resistance vs. I_D


Fig.7 Capacitance Characteristics

Fig.8 Gate Charge Characteristics

Fig.9 Normalized Transient Impedance

Fig.10 Maximum Safe Operation Area

Fig.11 Switching Time Waveform

Fig.12 Gate Charge Waveform

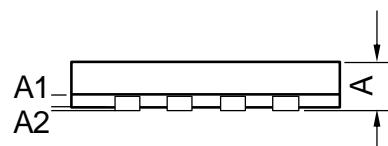
DFN3.3X3.3 PACKAGE INFORMATION



BOTTOM VIEW



TOP VIEW



SIDE VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.800	0.700	0.031	0.028
A1	0.250	0.150	0.010	0.006
A2	0.050	---	0.002	---
D	3.400	3.200	0.134	0.126
E	3.400	3.200	0.134	0.126
D1	2.850	2.650	0.112	0.104
E1	2.250	2.000	0.089	0.079
b	0.400	0.250	0.016	0.010
L	0.600	0.400	0.024	0.016
L1	0.350 BSC		0.014 BSC	
k	0.500	0.250	0.020	0.010
e	0.65BSC		0.026BSC	

DFN3.3X3.3 RECOMMENDED LAND PATTERN

